826467-8 ! PENDING OBSOLESCENCE

AMPMODU | AMPMODU Headers

TE Internal #: 826467-8 TE Internal Description: 8P MOD II SHROUDED HEADER, ST View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	8
Number of Rows	1
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
PCB Contact Termination Area Plating Material Thickness	3 µm
Mating Pin Diameter	.63 mm[.025 in]

C For support call+1 800 522 6752



Conset Snace & Form Round Conset Underplating Material Nickel PCB Contact Termination Area Plating Material Tin Conset Masing Area Plating Material Gold Flash over Pailadium Nickel Conset Masing Area Plating Material Gold Flash over Pailadium Nickel Conset Masing Area Plating Material Trickness & µm(31.5 µn) Conset Under Masing Area Plating Material Trickness & µm(31.5 µn) Conset Current Rating (Max) 3 A Termination Features 3 2 mm(126 in) Term mation Post & Tal Length 3 2 mm(126 in) Term nation Post & Tal Length 3 2 mm(126 in) Term mation Post & Tal Length 3 2 mm(126 in) Maring Retention With Maring Retention Type Desent latching Maring Argument With Maring Argument Type Pelarization PCR Mount Retention Without PCR Mount Retention Without PCR Mount Retention Polarization PCR Mount Retention Sold Mount Polarization Sold Mount Polaring Temperature Rating J.57 mm(11n)		
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Industry Standards

Compatible With Agency/Standards Products	CSA
Compatible With Approved Standards Products	CSA LR7189, CUL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	150
Packaging Method	Carton
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900

Solder Process Capability

ppm.

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

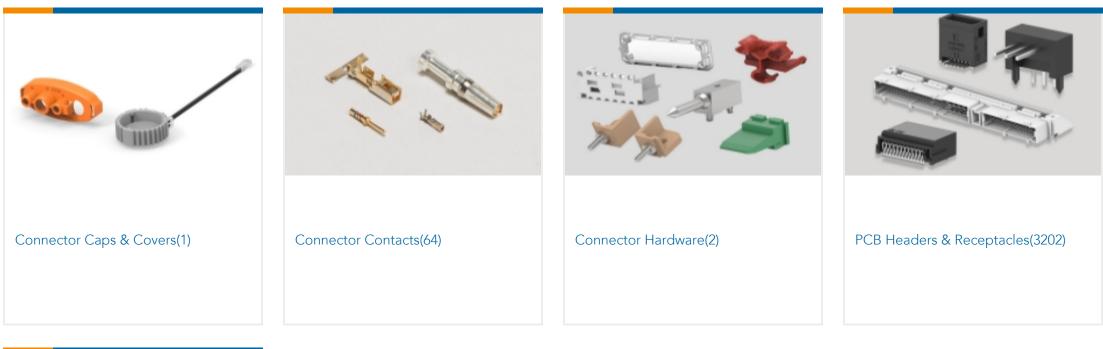
Compatible Parts

8P MOD II SHROUDED HEADER, ST





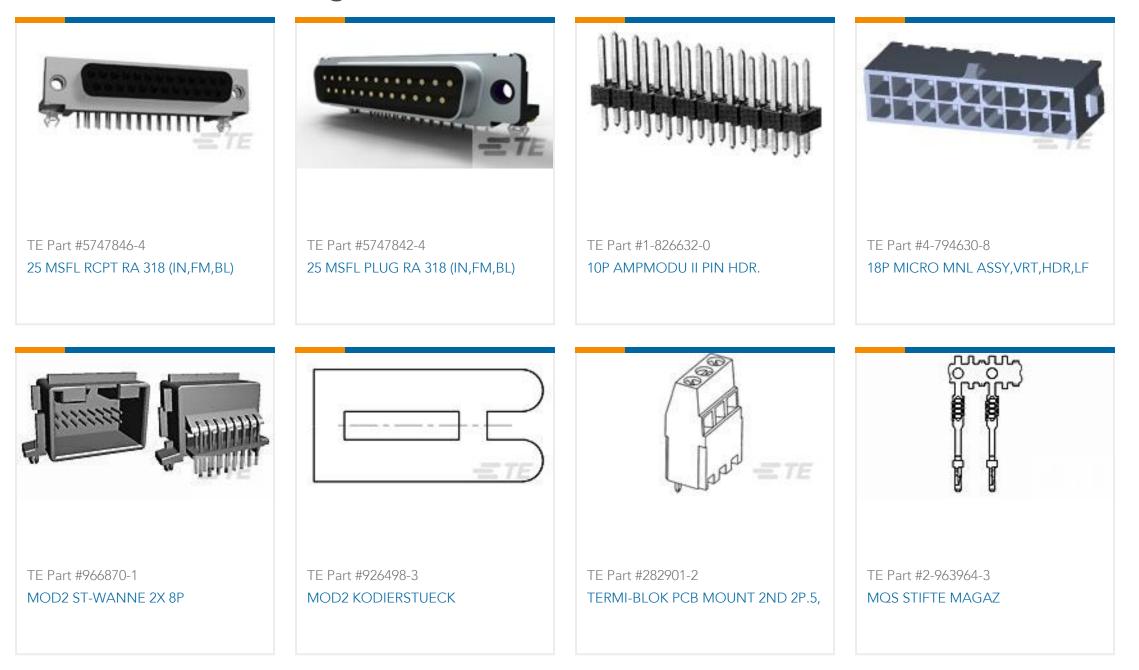
Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies & Housings(5)

Customers Also Bought



8P MOD II SHROUDED HEADER, ST





Documents

Product Drawings 8P MOD II SHROUDED HEADER, ST

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_826467-8_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_826467-8_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_826467-8_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the $\ensuremath{\text{Terms}}$ and $\ensuremath{\text{Conditions}}$ of use.

Agency Approvals UL Report

English